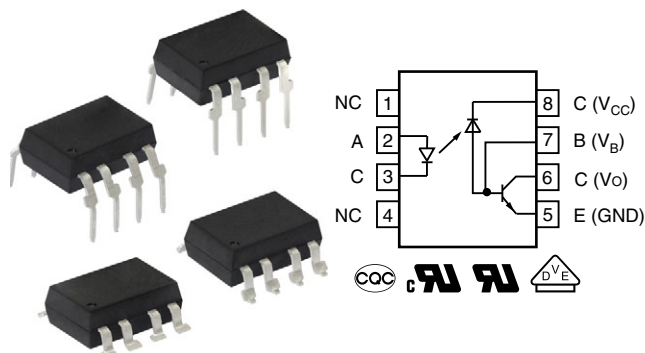


High Speed Optocoupler, 1 MBd, Transistor Output



FEATURES

- Isolation test voltage 5300 V_{RMS}
- TTL compatible
- High bit rates: 1 MBit/s
- High common mode interference immunity
- Bandwidth 2 MHz
- Open collector output
- External base wiring possible
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912


RoHS
COMPLIANT

LINKS TO ADDITIONAL RESOURCES



Related Documents



Design Tools



3D Models



Footprints



Schematics

SPICE

Models

AGENCY APPROVALS

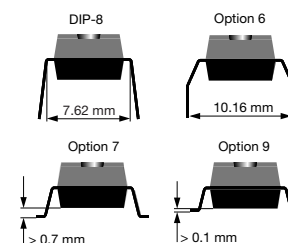
- [UL](#)
- [cUL](#)
- [DIN EN 60747-5-5 \(VDE 0884-5\)](#), available with option 1
- [CQC](#)

DESCRIPTION

The SFH6136 optocoupler features a high signal transmission rate and a high isolation resistance. It has a GaAlAs infrared emitting diode, optically coupled with an integrated photo detector which consists of a photo diode and a high speed transistor in a DIP-8 plastic package. Signals can be transmitted between two electrically separated circuits up to frequencies of 2 MHz. The potential difference between the circuits to be coupled should not exceed the maximum permissible reference voltages.

ORDERING INFORMATION

S	F	H	6	1	3	6	-	X	0	#	#	T
PART NUMBER								PACKAGE OPTION			TAPE AND REEL	



AGENCY CERTIFIED / PACKAGE	CTR (%)
UL, cUL, CQC	≥ 19
DIP-8	SFH6136
SMD-8, option 9	SFH6136-X009T
UL, cUL, CQC, VDE (option 1)	≥ 19
DIP-8	SFH6136-X001
DIP-8, 400 mil, option 6	SFH6136-X016
SMD-8, option 7	SFH6136-X017T ⁽¹⁾

Notes

- Additional options may be possible, please contact sales office
- ⁽¹⁾ Also available in tubes; do not add T to end



ABSOLUTE MAXIMUM RATINGS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)				
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
INPUT				
Reverse voltage		V_R	3	V
Forward current		I_F	25	mA
Peak forward current	$t = 1\text{ ms}$, duty cycle 50 %	I_{FM}	50	mA
Maximum surge forward current	$t \leq 1\text{ }\mu\text{s}$, 300 pulses/s	I_{FSM}	1	A
Thermal resistance		R_{thja}	700	K/W
Power dissipation		P_{diss}	45	mW
OUTPUT				
Supply voltage		V_S	-0.5 to 30	V
Output voltage		V_O	-0.5 to 25	V
Emitter base voltage		V_{EBO}	5	V
Output current		I_O	8	mA
Maximum output current		I_O	16	mA
Base current		I_B	5	mA
Thermal resistance		R_{thja}	300	K/W
Power dissipation	$T_{amb} = 70\text{ }^{\circ}\text{C}$	P_{diss}	100	mW
COUPLER				
Isolation test voltage		V_{ISO}	5300	V_{RMS}
Pollution degree (DIN VDE 0110)			2	
Isolation resistance	$V_{IO} = 500\text{ V}$, $T_{amb} = 25\text{ }^{\circ}\text{C}$	R_{IO}	$\geq 10^{12}$	Ω
	$V_{IO} = 500\text{ V}$, $T_{amb} = 100\text{ }^{\circ}\text{C}$	R_{IO}	$\geq 10^{11}$	Ω
Storage temperature range		T_{stg}	-55 to +125	$^{\circ}\text{C}$
Ambient temperature range		T_{amb}	-55 to +100	$^{\circ}\text{C}$
Soldering temperature ⁽¹⁾	Max. $\leq 10\text{ s}$, dip soldering $\geq 0.5\text{ mm}$ distance from case bottom	T_{sld}	260	$^{\circ}\text{C}$

Notes

- Stresses in excess of the absolute maximum ratings can cause permanent damage to the device. Functional operation of the device is not implied at these or any other conditions in excess of those given in the operational sections of this document. Exposure to absolute maximum ratings for extended periods of the time can adversely affect reliability.

⁽¹⁾ Refer to wave profile for soldering conditions for through hole devices

ELECTRICAL CHARACTERISTICS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
INPUT						
Forward voltage	$I_F = 16\text{ mA}$	V_F	-	1.6	1.9	V
Breakdown voltage	$I_R = 10\text{ }\mu\text{A}$	V_{BR}	3	-	-	V
Reverse current	$V_R = 3\text{ V}$	I_R	-	0.5	10	μA
Capacitance	$V_R = 0\text{ V}$, $f = 1\text{ MHz}$	C_O	-	125	-	pF
Temperature coefficient of forward voltage	$I_F = 16\text{ mA}$	$\Delta V_F / \Delta T_{amb}$	-	1.7	-	mV/ $^{\circ}\text{C}$
OUTPUT						
Logic low supply current	$I_F = 16\text{ mA}$, $V_O = \text{open}$, $V_{CC} = 15\text{ V}$	I_{CCL}	-	150	-	μA
Logic high supply current	$I_F = 0\text{ V}$, $V_O = \text{open}$, $V_{CC} = 15\text{ V}$	I_{CCH}	-	0.01	1	μA
Output voltage, output low	$I_F = 16\text{ mA}$, $V_{CC} = 4.5\text{ V}$, $I_O = 2.4\text{ mA}$	V_{OL}	-	0.1	0.4	V
Output current, output high	$I_F = 0\text{ mA}$, $V_O = V_{CC} = 5.5\text{ V}$	I_{OH}	-	3	500	nA
	$I_F = 0\text{ mA}$, $V_O = V_{CC} = 15\text{ V}$	I_{OH}	-	0.01	1	μA
COUPLER						
Capacitance (input to output)	$f = 1\text{ MHz}$	C_{IO}	-	0.6	-	pF

Note

- Minimum and maximum values are testing requirements. Typical values are characteristics of the device and are the result of engineering evaluation. Typical values are for information only and are not part of the testing requirements.

CURRENT TRANSFER RATIO

PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Current transfer ratio	$I_F = 16 \text{ mA}$, $V_O = 0.4 \text{ V}$, $V_{CC} = 4.5 \text{ V}$	CTR	19	35	-	%
	$I_F = 16 \text{ mA}$, $V_O = 0.5 \text{ V}$, $V_{CC} = 4.5 \text{ V}$	CTR	15	-	-	%

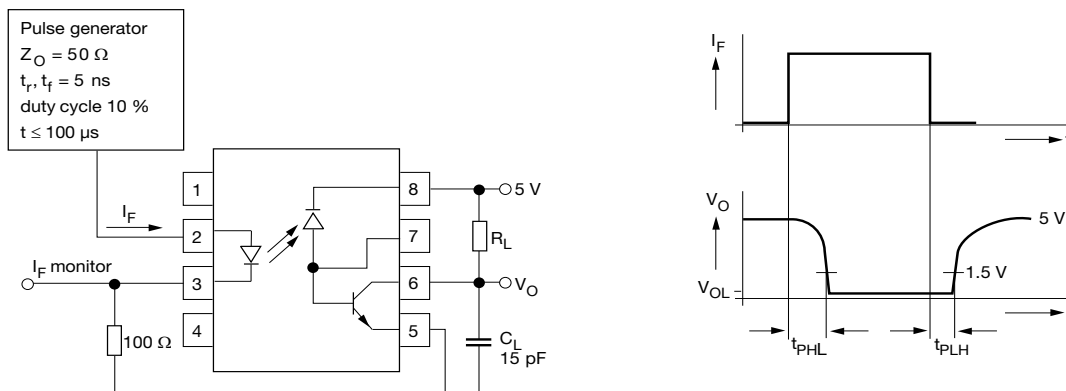


Fig. 1 - Schematics

SWITCHING CHARACTERISTICS

PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
High to low	$I_F = 16 \text{ mA}$, $V_{CC} = 5 \text{ V}$, $R_L = 1.9 \text{ k}\Omega$	t_{PHL}	-	0.2	0.8	μs
Low to high	$I_F = 16 \text{ mA}$, $V_{CC} = 5 \text{ V}$, $R_L = 1.9 \text{ k}\Omega$	t_{PLH}	-	0.2	0.8	μs

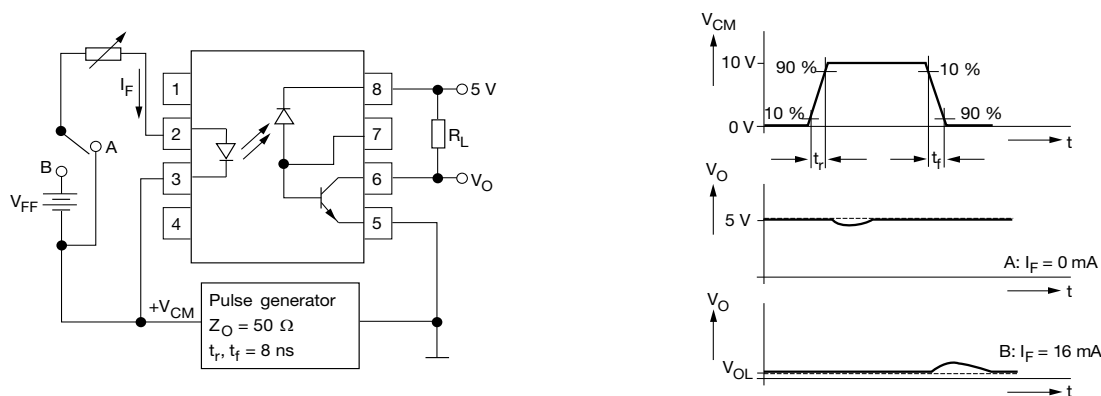


Fig. 2 - Common Mode Interference Immunity

COMMON MODE TRANSIENT IMMUNITY

PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
High	$V_{CM} = 10 \text{ V}_{P-P}$, $V_{CC} = 5 \text{ V}$, $I_F = 0 \text{ mA}$, $R_L = 1.9 \text{ k}\Omega$	CM_H	-	1000	-	$\text{V}/\mu\text{s}$
Low	$V_{CM} = 10 \text{ V}_{P-P}$, $V_{CC} = 5 \text{ V}$, $I_F = 0 \text{ mA}$, $R_L = 1.9 \text{ k}\Omega$	CM_L	-	1000	-	$\text{V}/\mu\text{s}$

SAFETY AND INSULATION RATINGS

PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Climatic classification (according to IEC 68 part 1)			-	55 / 100 / 21	-	
Comparative tracking index		CTI	175	-	399	
V_{IOTM}			8000	-	-	V
V_{IORM}			890	-	-	V
P_{SO}			-	-	500	mW
I_{SI}			-	-	300	mA
T_{SI}			-	-	175	°C
Creepage distance	Standard DIP-8		7	-	-	mm
Clearance distance	Standard DIP-8		7	-	-	mm
Creepage distance	400 mil DIP-8		8	-	-	mm
Clearance distance	400 mil DIP-8		8	-	-	mm

Note

- As per IEC 60747-5-5, §7.4.3.8.1, this optocoupler is suitable for “safe electrical insulation” only within the safety ratings. Compliance with the safety ratings shall be ensured by means of protective circuits.

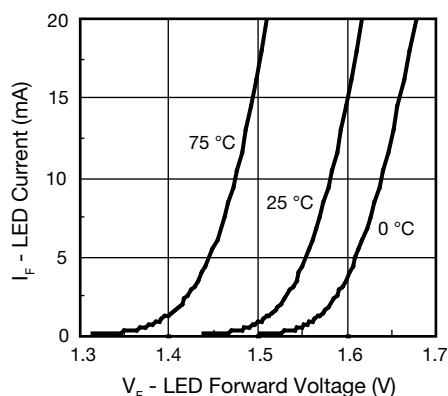
TYPICAL CHARACTERISTICS ($T_{amb} = 25\text{ °C}$, unless otherwise specified)


Fig. 3 - LED Forward Current vs. Forward Voltage

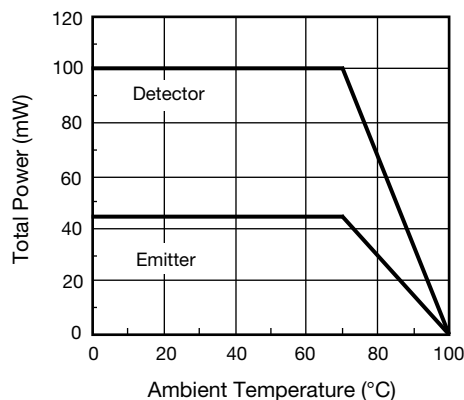


Fig. 5 - Permissible Power Dissipation vs. Temperature

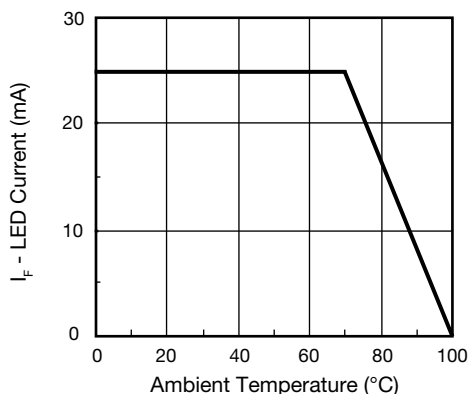


Fig. 4 - Permissible Forward LED Current vs. Temperature

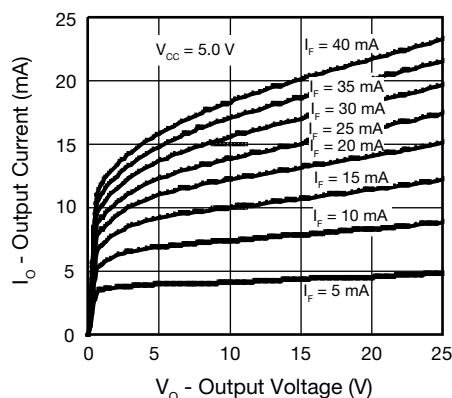


Fig. 6 - Output Current vs. Output Voltage

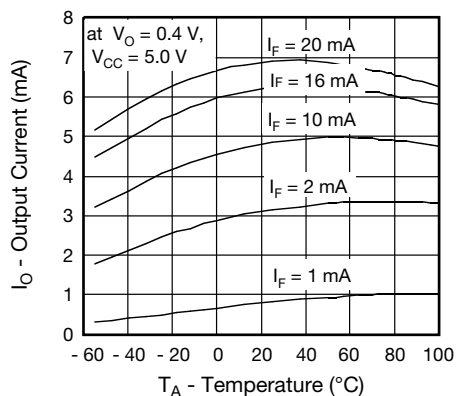


Fig. 7 - Output Current vs. Temperature

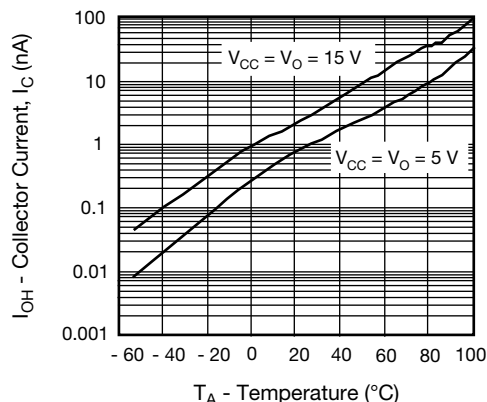


Fig. 10 - Logic High Output Current vs. Temperature

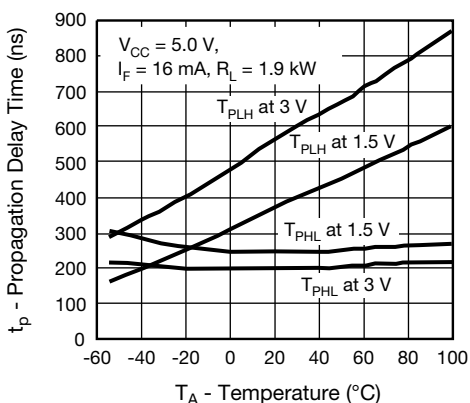


Fig. 8 - Propagation Delay vs. Ambient Temperature

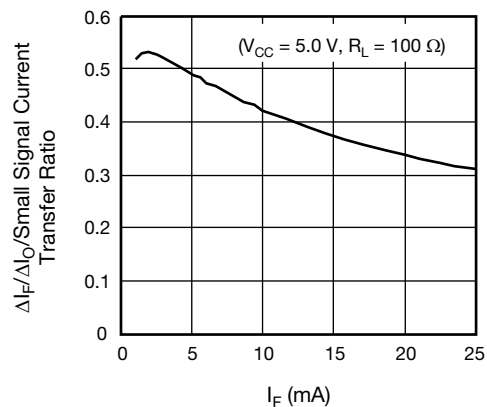


Fig. 11 - Small Signal Current Transfer Ratio vs. Quiescent Input Current

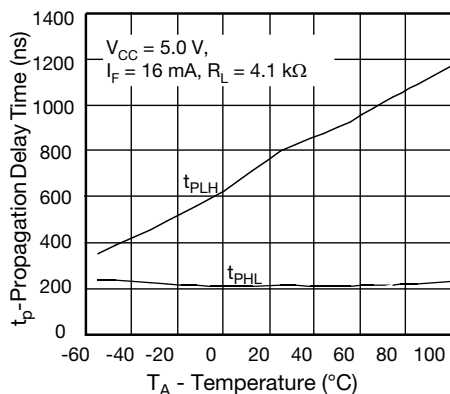
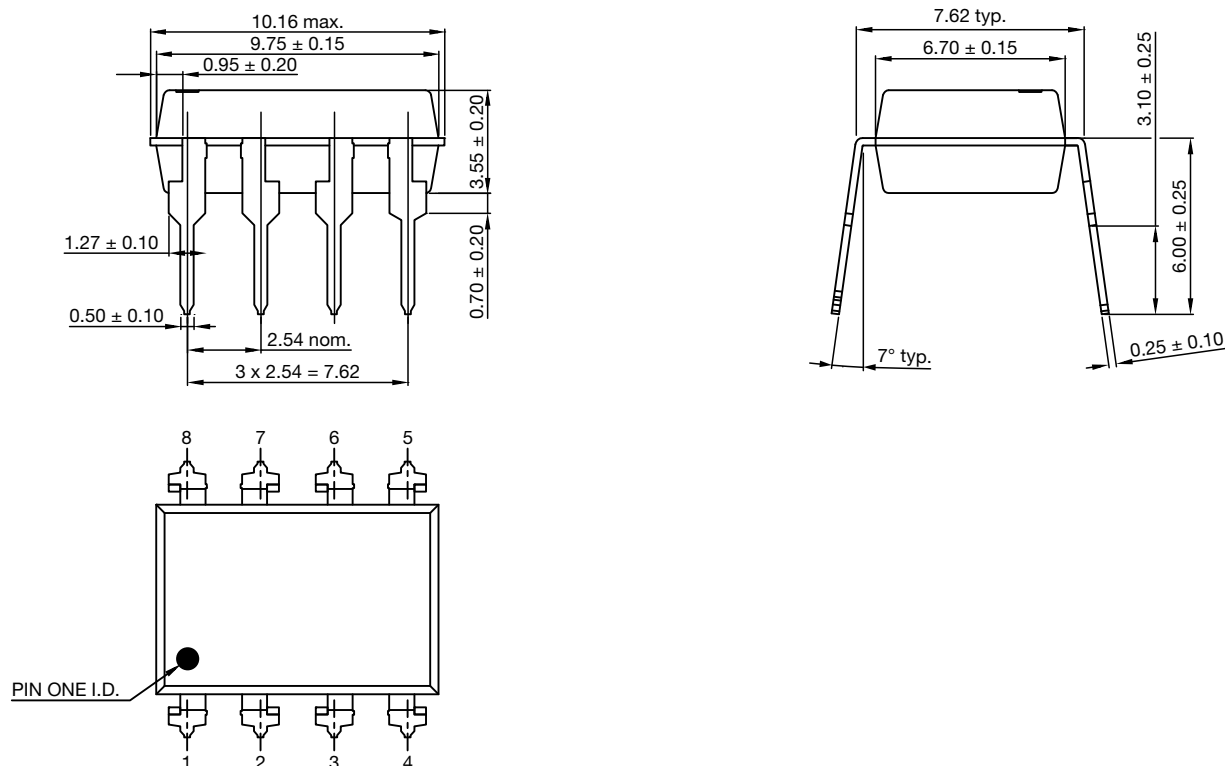


Fig. 9 - Propagation Delay vs. Ambient Temperature

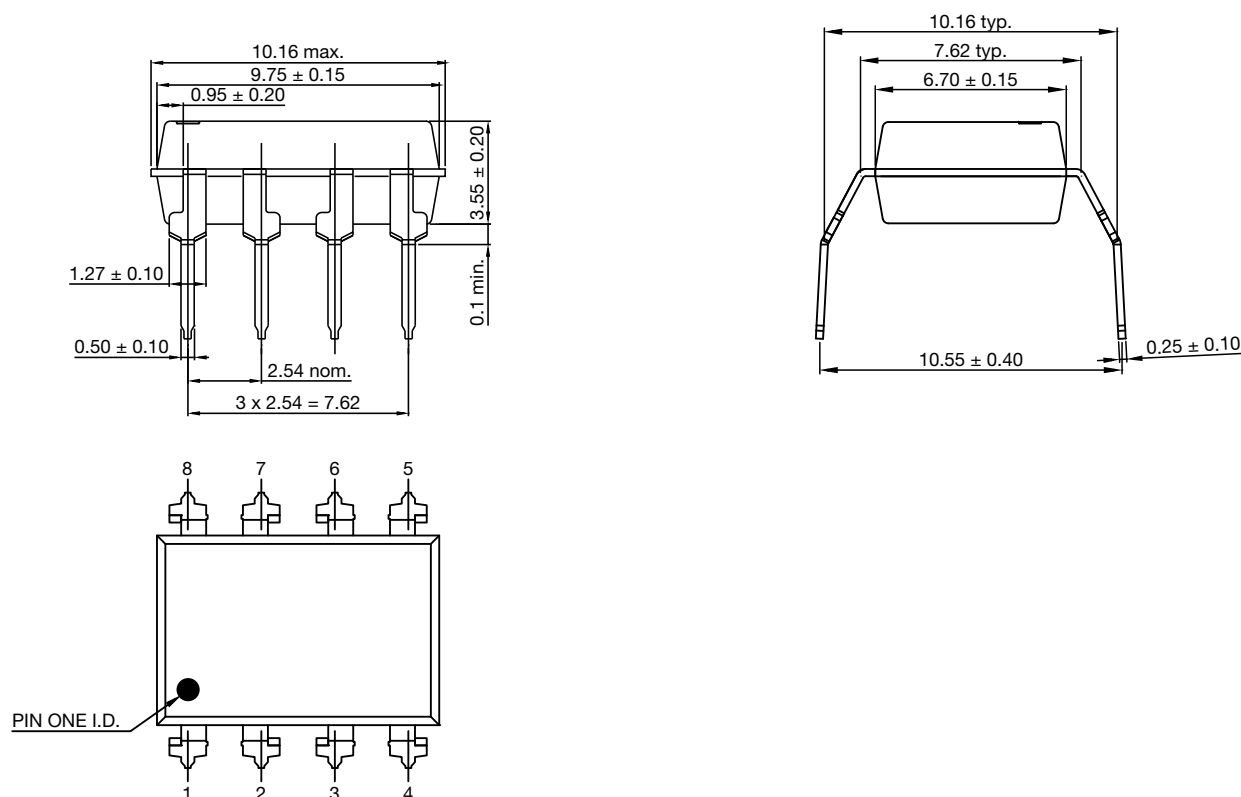


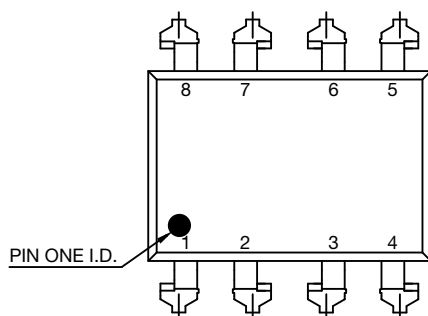
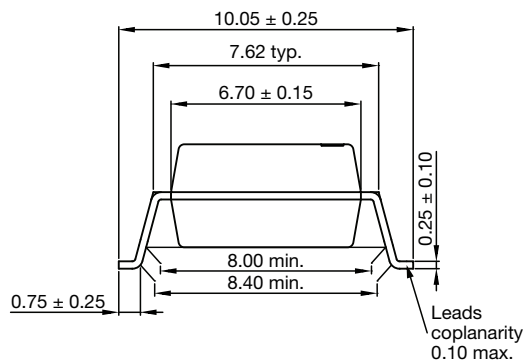
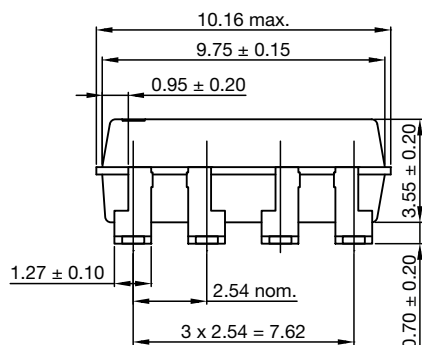
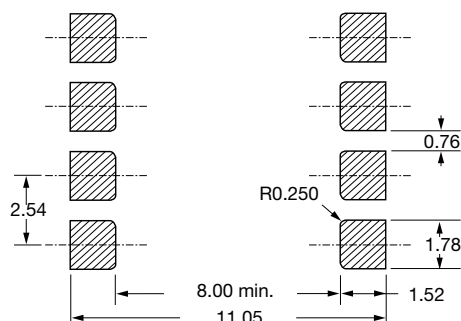
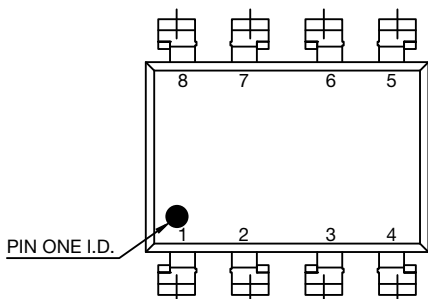
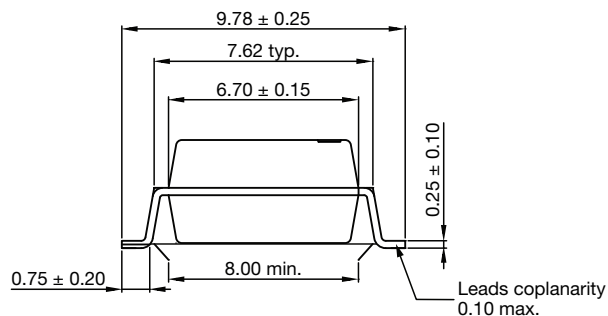
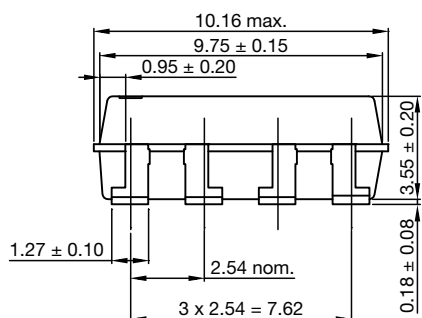
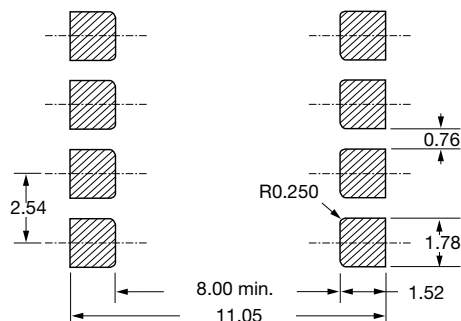
PACKAGE DIMENSIONS (in millimeters)

DIP-8



DIP-8, 400 mil (option 6)



SMD-8 (option 7)

Recommended Footprint

SMD-8 (option 9)

Recommended Footprint


PACKAGE MARKING

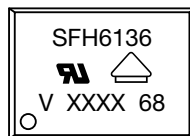


Fig. 12 - Example of SFH6136-X017T

Notes

- XXXX = LMC (lot marking code)
- VDE logo is only marked on option 1 parts
- Tape and reel suffix (T) is not part of the package marking

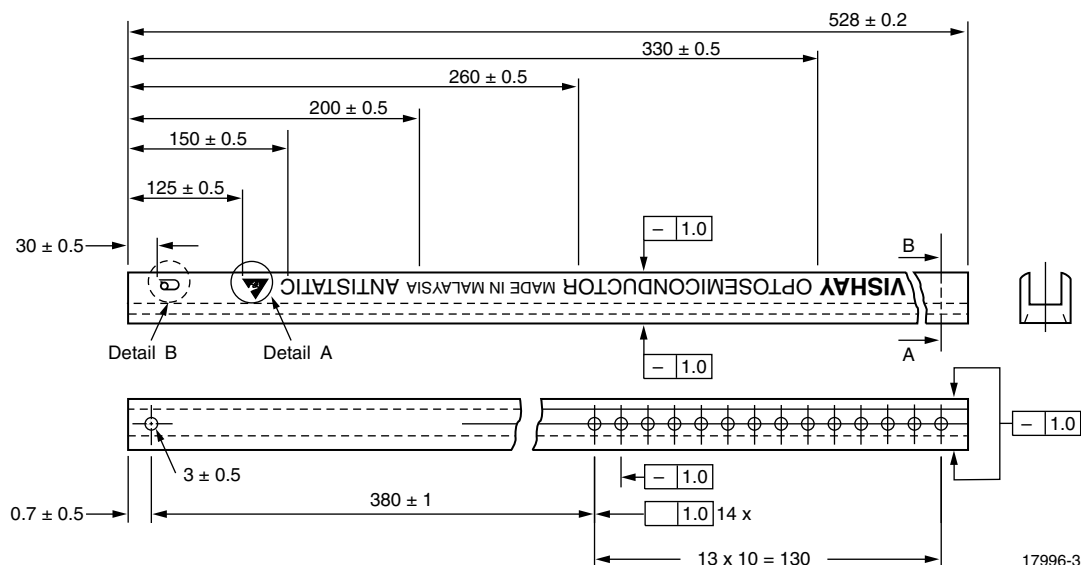
PACKING INFORMATION (in millimeters)**Tube**

Fig. 13 - Shipping Tube Specifications for DIP-8 Packages

DEVICES PER TUBS			
TYPE	UNITS/TUBE	TUBES/BOX	UNITS/BOX
DIP-8	50	40	2000

DIP-8

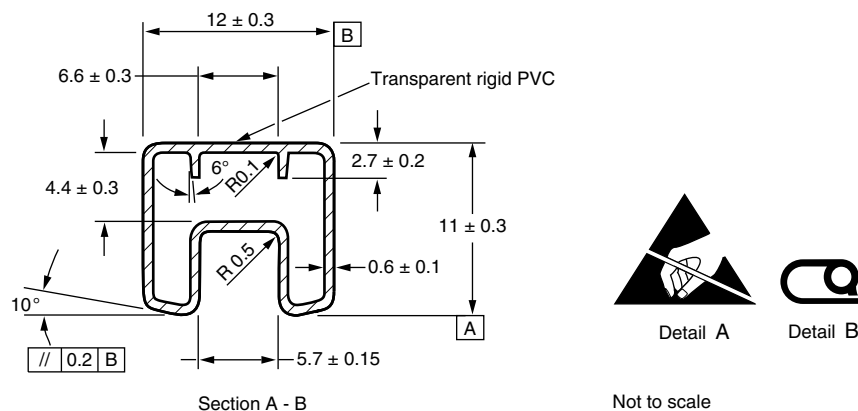


Fig. 14 - Tube Shipping Medium

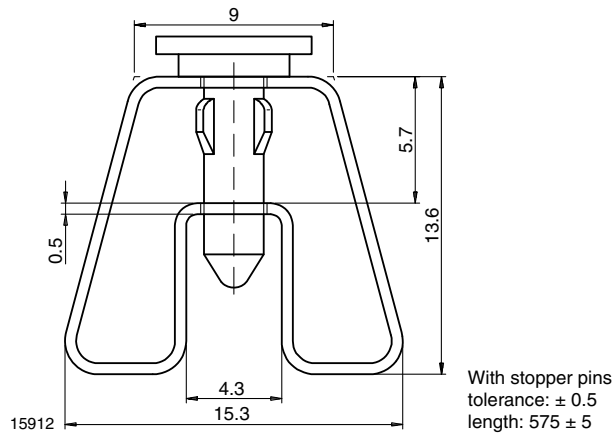
DIP-8, 400 mil (option 6)


Fig. 15 - Tube Shipping Medium

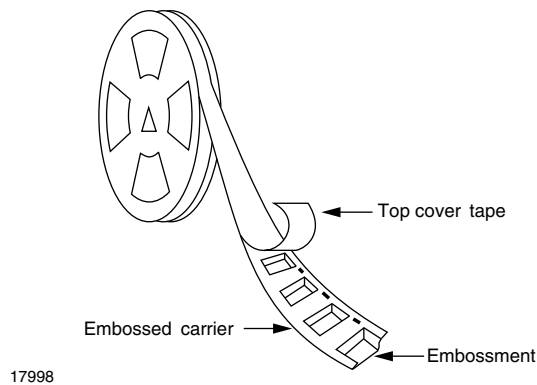
Tape and Reel


Fig. 16 - Tape and Reel Shipping Medium

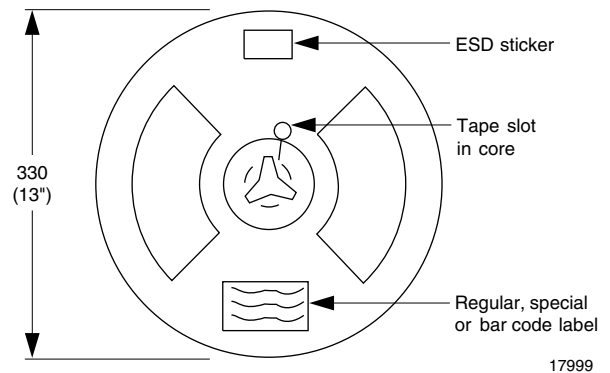


Fig. 17 - Tape and Reel Shipping Medium

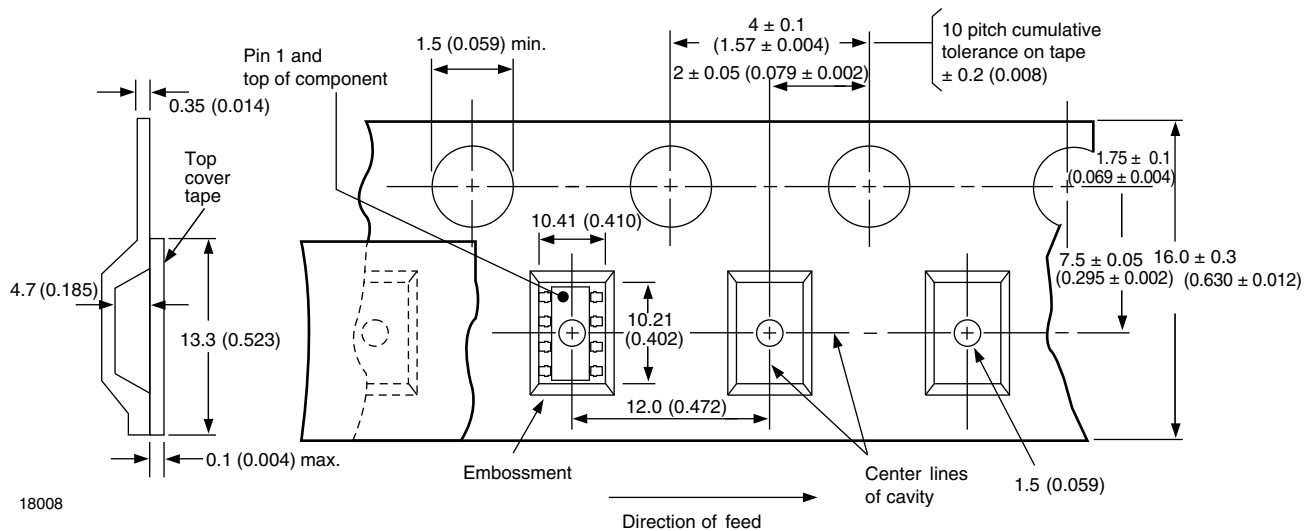
SMD-8 (option 7)


Fig. 18 - Tape and Reel Packing (1000 pieces on Reel)

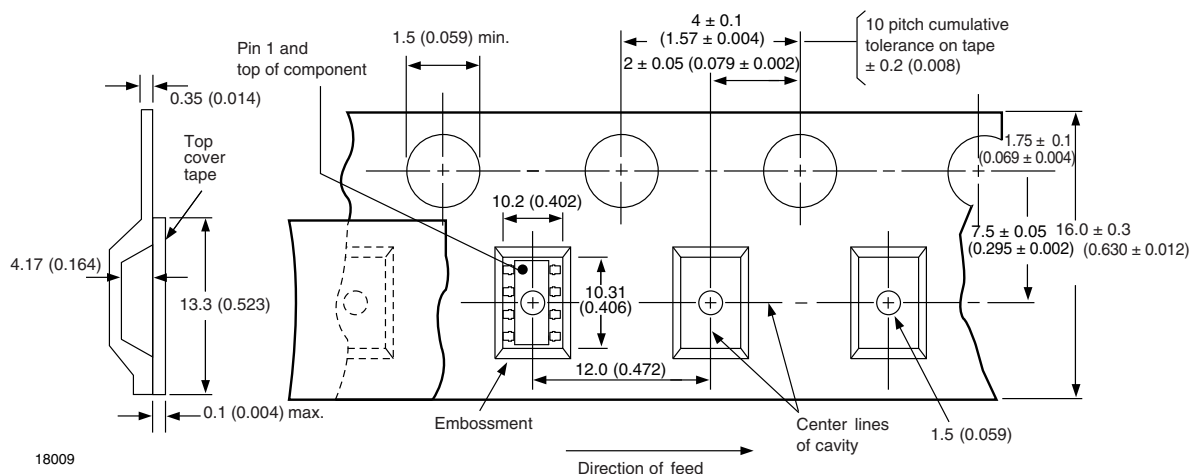
SMD-8 (option 9)


Fig. 19 - Tape and Reel Shipping Medium

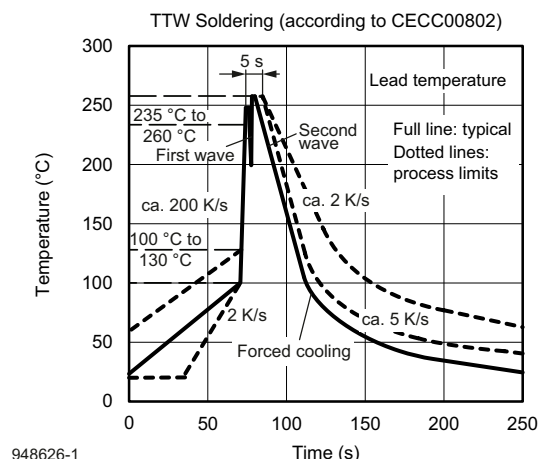
SOLDER PROFILES


Fig. 20 - Wave Soldering Double Wave Profile According to J-STD-020 for DIP Devices

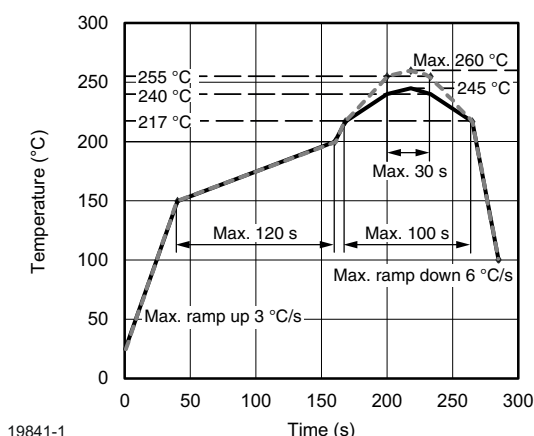


Fig. 21 - Lead (Pb)-free Reflow Solder Profile According to J-STD-020 for SMD Devices

HANDLING AND STORAGE CONDITIONS

ESD level: HBM class 2

Floor life: unlimited

Conditions: $T_{amb} < 30\text{ °C}$, RH < 85 %

Moisture sensitivity level 1, according to J-STD-020



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